

### REMARKS

Claims 1, 2, 4, 9, 11, 15, 19-21, and 23 are pending with claims 1, 9, 15, and 20 being independent. Claims 1, 9, 15 and 20 have been amended. Claims 3, 5-8, 10, 12-14, 16-18, 22, and 24-27 have been or were previously canceled.

The Examiner has objected to claims 1, 5, 9, 12, 15, 20, and 24 as being unclear. Applicants have amended claims 1, 9, 15, and 20 to address the Examiner's concerns by omitting the limitation of "at a boundary". Claims 5, 12, and 24 have been canceled, rendering this rejection moot as applied to these claims.

Independent claims 1, 9, 15, and 20 and dependent claims 2, 4, 6, 11, 19, 21, and 23 have been rejected as being unpatentable over Lee (U.S. Patent No. 5,589,713) in view of Applicants' Admitted Prior Art (AAPA).

Claims 1, 9, 15, and 20 have been amended to recite "an alloy comprising at least one selected from the group consisting of Ga and Sb." Applicants request reconsideration and withdrawal of the rejection of claims 1, 9, 15, and 20 and their dependent claims because neither Lee, AAPA, nor any combination of the two describes or suggests the recited alloy. Instead, Lee describes using Ge, Mg, Sn, In, Pb, and Zn to lower the melting point of the material of the first conductive layer 39a (col. 7, lines 33-40, and col. 9, lines 30-43), while the AAPA is silent as to this feature.

Applicants submit that all claims are in condition for allowance.